

ABSTRACT

A multi-layer printed wiring board including a first substrate having an opening and having external terminals positioned to be connected to a package substrate, a second substrate laminated to the first substrate and having external terminals positioned to be connected to a mother board, the second substrate having a metallic layer portion in the opening of the first substrate and non-through holes filled with conductive material and connected to the metallic layer portion, and an IC component having terminals and loaded in the opening of the first substrate such that the terminals of the IC component face an opposite side of the metallic layer portion of the second substrate. The IC chip is accommodated in the opening such that the metallic layer portion and non-through holes of the second substrate irradiate heat generated by the IC chip.